**Important notice**

Dear Customer,

On 7 February 2017 the former NXP Standard Product business became a new company with the tradename **Nexperia**. Nexperia is an industry leading supplier of Discrete, Logic and PowerMOS semiconductors with its focus on the automotive, industrial, computing, consumer and wearable application markets

In data sheets and application notes which still contain NXP or Philips Semiconductors references, use the references to Nexperia, as shown below.

Instead of http://www.nxp.com, http://www.philips.com/ or http://www.semiconductors.philips.com/, use **http://www.nexperia.com**

Instead of sales.addresses@www.nxp.com or sales.addresses@www.semiconductors.philips.com, use **salesaddresses@nexperia.com** (email)

Replace the copyright notice at the bottom of each page or elsewhere in the document, depending on the version, as shown below:
- © NXP N.V. (year). All rights reserved or © Koninklijke Philips Electronics N.V. (year). All rights reserved
Should be replaced with:
- **© Nexperia B.V. (year). All rights reserved**.

If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

# DATA SHEET

# PRLL5817; PRLL5818; PRLL5819
## Schottky barrier diodes

Product data sheet
Supersedes data of 1996 May 03

1999 Apr 22

# Schottky barrier diodes

# PRLL5817; PRLL5818; PRLL5819

## FEATURES

- Low switching losses
- Fast recovery time
- Guard ring protected
- Hermetically sealed glass SMD package.

## APPLICATIONS

- Low power, switched-mode power supplies
- Rectifying
- Polarity protection.

## DESCRIPTION

The PRLL5817 to PRLL5819 types are Schottky barrier diodes fabricated in planar technology, and encapsulated in SOD87 hermetically sealed glass SMD packages incorporating Implotec$^{TM(1)}$ technology.

(1) Implotec is a trademark of Philips.

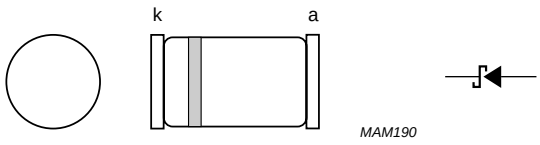



Fig.1 Simplified outline (SOD87) and symbol.

## MARKING

| TYPE NUMBER | MARKING CODE |
|---|---|
| PRLL5817 | 9 |
| PRLL5818 | 9 |
| PRLL5819 | 9 |

**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|---|---|---|---|---|---|
| $V_R$ | continuous reverse voltage | | | | |
| | PRLL5817 | | – | 20 | V |
| | PRLL5818 | | – | 30 | V |
| | PRLL5819 | | – | 40 | V |
| $V_{RSM}$ | non-repetitive peak reverse voltage | | | | |
| | PRLL5817 | | – | 24 | V |
| | PRLL5818 | | – | 36 | V |
| | PRLL5819 | | – | 48 | V |
| $V_{RRM}$ | repetitive peak reverse voltage | | | | |
| | PRLL5817 | | – | 20 | V |
| | PRLL5818 | | – | 30 | V |
| | PRLL5819 | | – | 40 | V |
| $V_{RWM}$ | crest working reverse voltage | | | | |
| | PRLL5817 | | – | 20 | V |
| | PRLL5818 | | – | 30 | V |
| | PRLL5819 | | – | 40 | V |
| $I_{F(AV)}$ | average forward current | $T_{amb}$ = 60 °C | – | 1 | A |
| $I_{FSM}$ | non-repetitive peak forward current | t = 10 ms half sine wave; $T_j = T_{j\,max}$ prior to surge: $V_R$ = 0 | – | 25 | A |
| $T_{stg}$ | storage temperature | | −65 | +175 | °C |
| $T_j$ | junction temperature | | – | 125 | °C |

## ELECTRICAL CHARACTERISTICS

$T_{amb}$ = 25 °C unless otherwise specified.

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---|---|---|---|---|---|---|
| $V_F$ | forward voltage | see Fig.2 | | | | |
| | PRLL5817 | $I_F$ = 0.1 A | – | – | 320 | mV |
| | | $I_F$ = 1 A | – | – | 450 | mV |
| | | $I_F$ = 3 A | – | – | 750 | mV |
| $V_F$ | forward voltage | see Fig.2 | | | | |
| | PRLL5818 | $I_F$ = 0.1 A | – | – | 330 | mV |
| | | $I_F$ = 1 A | – | – | 550 | mV |
| | | $I_F$ = 3 A | – | – | 875 | mV |
| $V_F$ | forward voltage | see Fig.2 | | | | |
| | PRLL5819 | $I_F$ = 0.1 A | – | – | 340 | mV |
| | | $I_F$ = 1 A | – | – | 600 | mV |
| | | $I_F$ = 3 A | – | – | 900 | mV |
| $I_R$ | reverse current | $V_R = V_{RRMmax}$; note 1 | – | 0.5 | 1 | mA |
| | | $V_R = V_{RRMmax}$; $T_j$ = 100 °C | – | 5 | 10 | mA |
| $C_d$ | diode capacitance | $V_R$ = 4 V; f = 1 MHz | | | | |
| | PRLL5817 | | – | 70 | – | pF |
| | PRLL5818 | | – | 50 | – | pF |
| | PRLL5819 | | – | 50 | – | pF |

**Note**

1. Pulse test: $t_p$ = 300 μs; δ = 0.02.

## THERMAL CHARACTERISTICS

| SYMBOL | PARAMETER | CONDITIONS | VALUE | UNIT |
|---|---|---|---|---|
| $R_{th\ j\text{-}a}$ | thermal resistance from junction to ambient | note 1 | 150 | K/W |

**Note**

1. Refer to SOD87 standard mounting conditions.

**GRAPHICAL DATA**

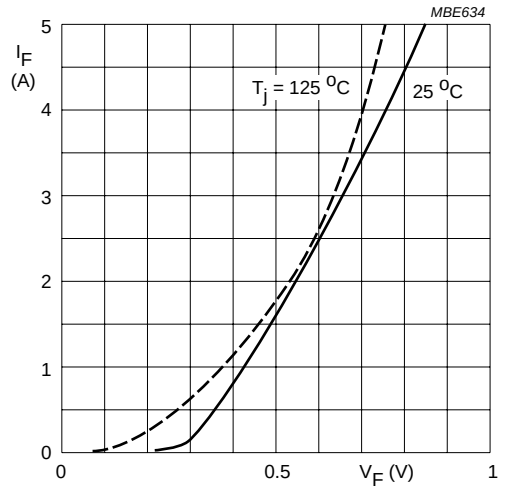



Fig.2 Typical forward voltage.

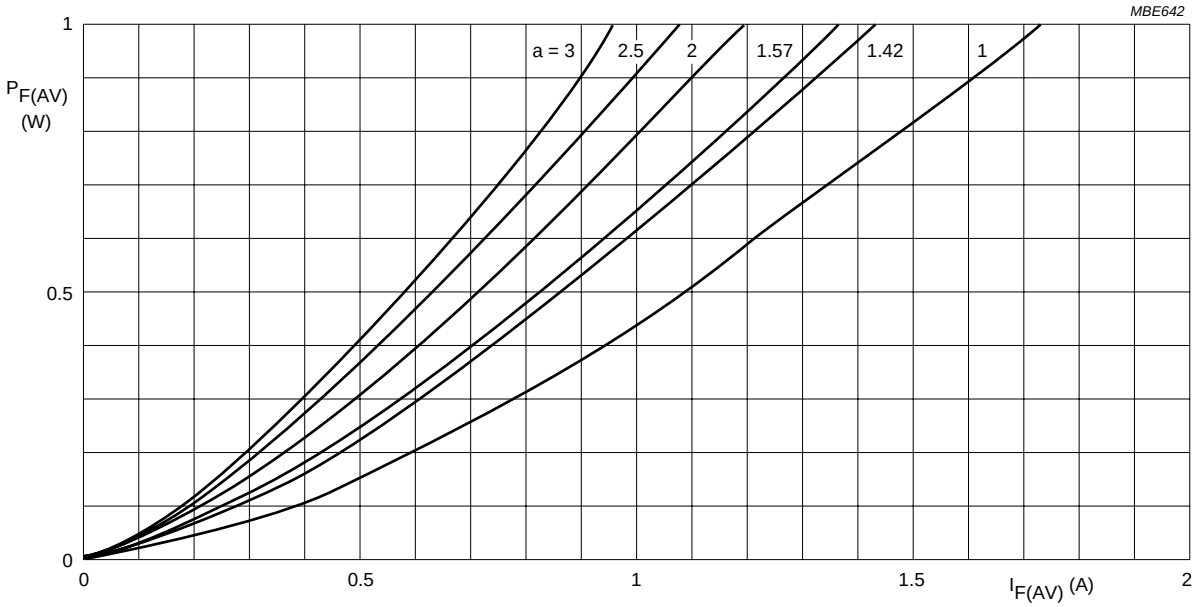



Fig.3 PRLL817. Maximum values steady state forward power dissipation as a function of the average forward current; $a = I_{F(RMS)}/I_{F(AV)}$.

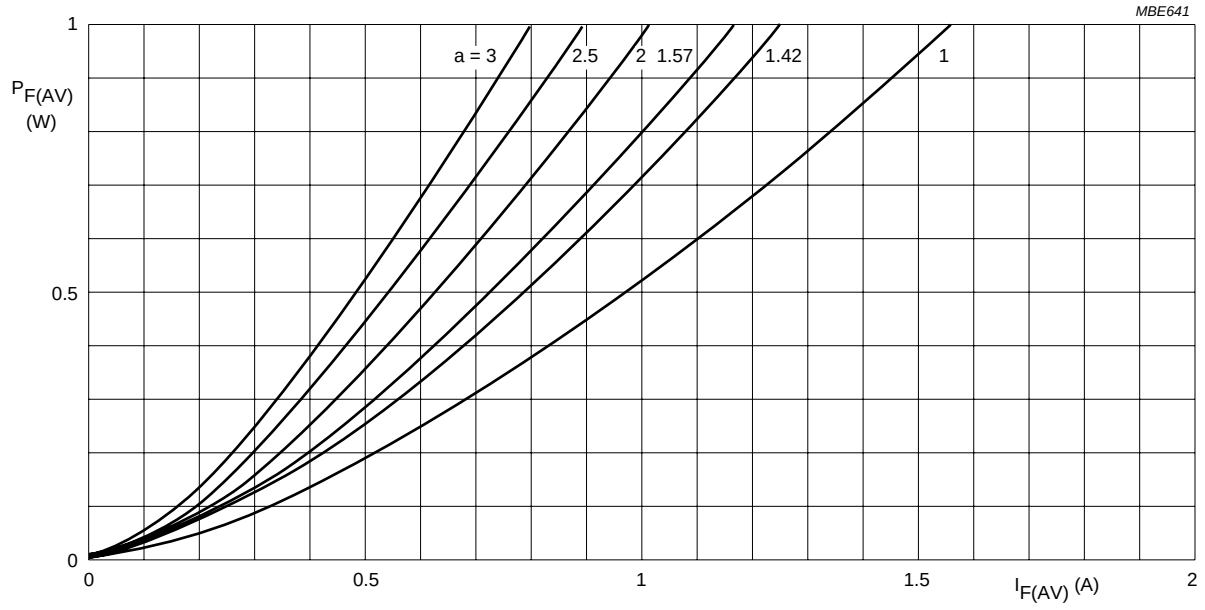



Fig.4 PRLL5818. Maximum values steady state forward power dissipation as a function of the average forward current; $a = I_{F(RMS)}/I_{F(AV)}$.

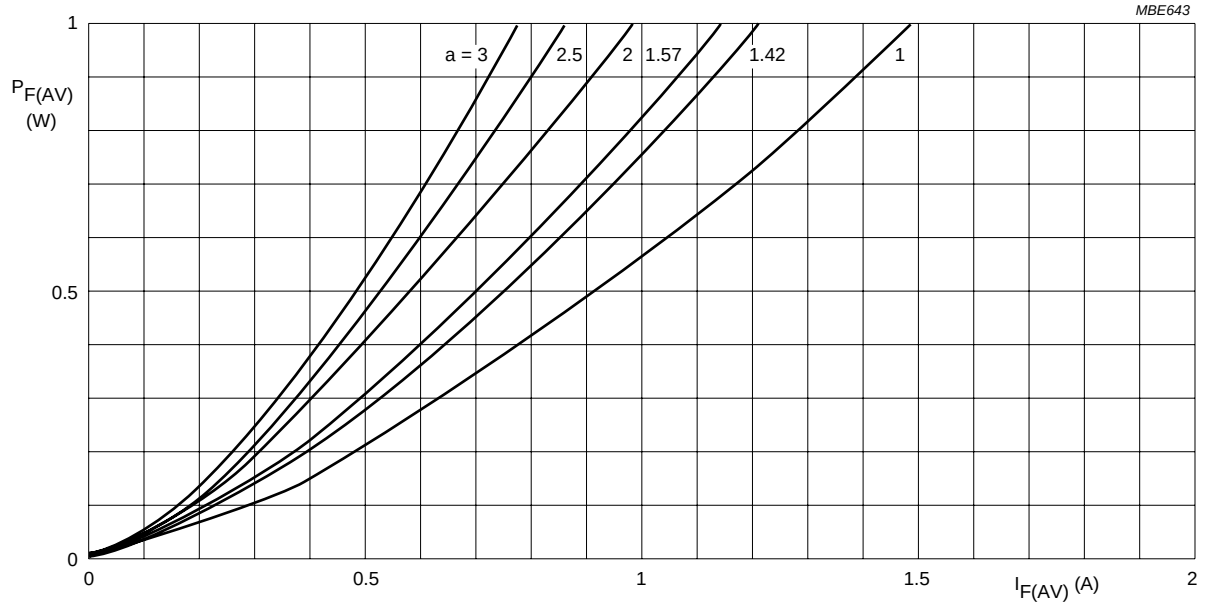



Fig.5 PRLL5819. Maximum values steady state forward power dissipation as a function of the average forward current; $a = I_{F(RMS)}/I_{F(AV)}$.

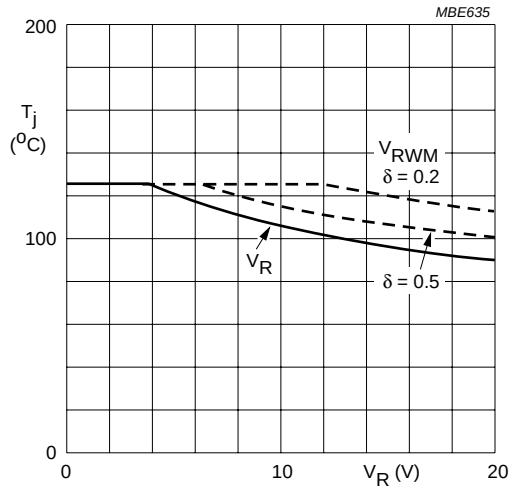



Fig.6 PRLL5817. Maximum permissible junction temperature as a function of reverse voltage; device mounted; refer to SOD87 standard mounting conditions.

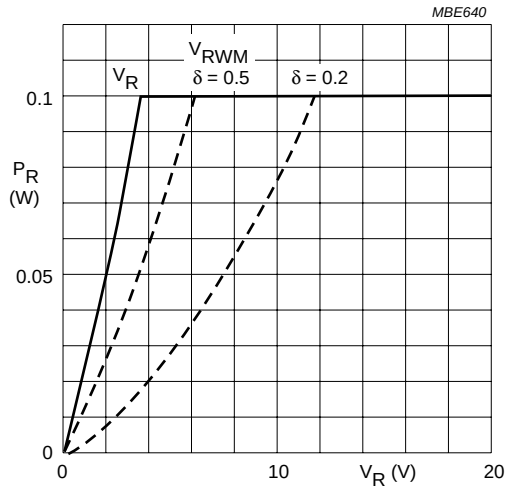



Fig.7 PRLL5817. Reverse power dissipation as a function of reverse voltage (max. values); device mounted; refer to SOD87 standard mounting conditions.

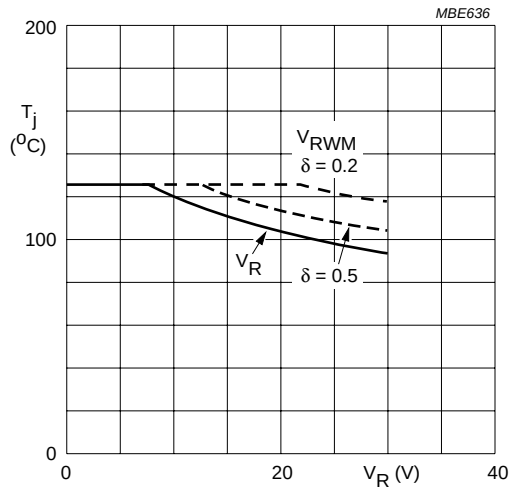



Fig.8 PRLL5818. Maximum permissible junction temperature as a function of reverse voltage; device mounted; refer to SOD87 standard mounting conditions.

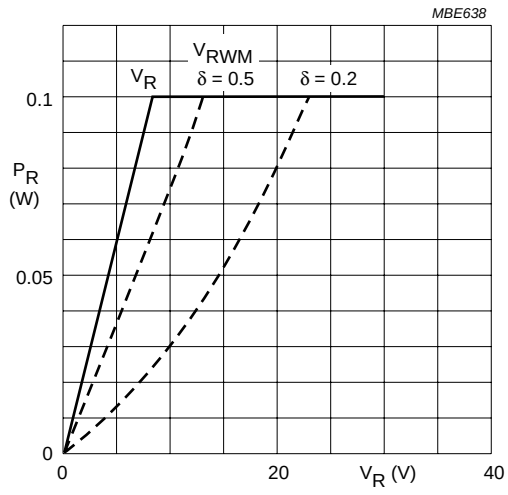



Fig.9 PRLL5818. Reverse power dissipation as a function of reverse voltage (max. values); device mounted; refer to SOD87 standard mounting conditions.

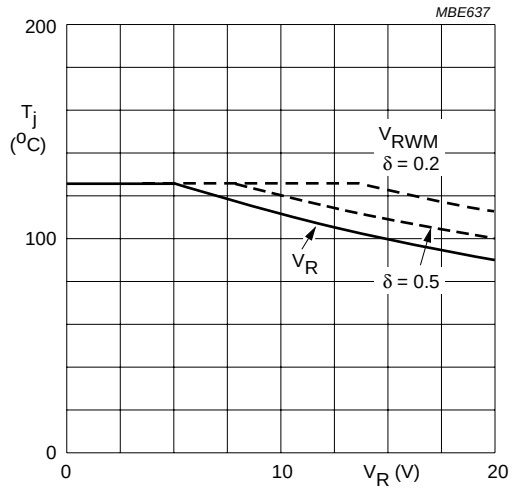



Fig.10 PRLL5819. Maximum permissible junction temperature as a function of reverse voltage; device mounted; refer to SOD87 standard mounting conditions.

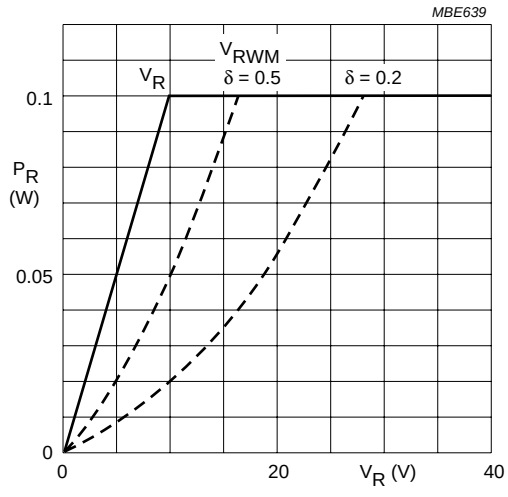
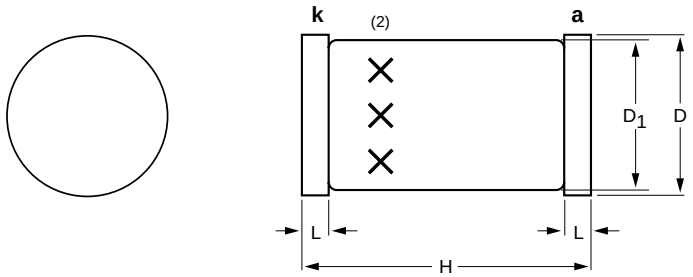



Fig.11 PRLL5819. Reverse power dissipation as a function of reverse voltage (max. values); device mounted; refer to SOD87 standard mounting conditions.

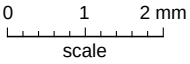
## PACKAGE OUTLINE

**Hermetically sealed glass surface mounted package; Implotec™(1) technology; 2 connectors** **SOD87**




**DIMENSIONS (mm are the original dimensions)**

| UNIT | D | D1 | H | L |
|---|---|---|---|---|
| mm | 2.1<br>2.0 | 2.0<br>1.8 | 3.7<br>3.3 | 0.3 |




**Notes**

1. Implotec is a trademark of Philips.
2. The marking indicates the cathode.

| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|---|---|---|---|---|---|---|
| | IEC | JEDEC | EIAJ | | | |
| SOD87 | 100H03 | | | | | ~~99-03-31~~<br>99-06-04 |

## DATA SHEET STATUS

| DOCUMENT STATUS[1] | PRODUCT STATUS[2] | DEFINITION |
|---|---|---|
| Objective data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary data sheet | Qualification | This document contains data from the preliminary specification. |
| Product data sheet | Production | This document contains the product specification. |

**Notes**

1. Please consult the most recently issued document before initiating or completing a design.
2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

## DISCLAIMERS

**General** — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

**Right to make changes** — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

**Suitability for use** — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in medical, military, aircraft, space or life support equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

**Applications** — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

**Limiting values** — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) may cause permanent damage to the device. Limiting values are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of this document is not implied. Exposure to limiting values for extended periods may affect device reliability.

**Terms and conditions of sale** — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at http://www.nxp.com/profile/terms, including those pertaining to warranty, intellectual property rights infringement and limitation of liability, unless explicitly otherwise agreed to in writing by NXP Semiconductors. In case of any inconsistency or conflict between information in this document and such terms and conditions, the latter will prevail.

**No offer to sell or license** — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

**Export control** — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from national authorities.

**Quick reference data** — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

# *NXP Semiconductors*

**Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

**Contact information**

For additional information please visit: **http://www.nxp.com**
For sales offices addresses send e-mail to: **salesaddresses@nxp.com**



Printed in The Netherlands 115002/00/02/pp11 Date of release: 1999 Apr 22 Document order number: 9397 750 05474